DATA SHEET



SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

NEC

The 2SK3642 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, and designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

ORDERING INFORMATION

PART NUMBER	PACKAGE		
2SK3642-ZK	TO-252 (MP-3ZK)		

FEATURES

- Low on-state resistance R_{DS(on)1} = 9.5 mΩ MAX. (V_{GS} = 10 V, I_D = 32 A) R_{DS(on)2} = 16 mΩ MAX. (V_{GS} = 4.5 V, I_D = 18 A)
- Low Ciss: Ciss = 1100 pF TYP.
- Built-in gate protection diode

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Drain to Source Voltage (VGs = 0 V)	VDSS	30	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	D(DC)	±64	А
Drain Current (pulse) Note1	D(pulse)	±190	А
Total Power Dissipation (Tc = 25°C)	Pt1	36	W
Total Power Dissipation	Pt2	1.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	–55 to + 150	°C
Single Avalanche Current Note2	las	25	А
Single Avalanche Energy Note2	Eas	62	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Starting T_{ch} = 25°C, V_{DD} = 15 V, R_G = 25 Ω , L = 100 μ H, V_{GS} = 20 \rightarrow 0 V

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The mark \star shows major revised points.

(TO-252)



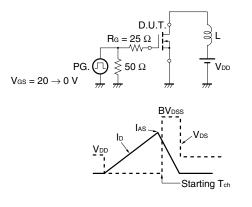
ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 30 V, V _{GS} = 0 V			10	μA
Gate Leakage Current	lgss	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.5		2.5	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = 10 V, I _D = 32 A	13	26		S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = 10 V, I _D = 32 A		7.6	9.5	mΩ
	RDS(on)2	V _{GS} = 4.5 V, I _D = 18 A		10.8	16	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V		1100		pF
Output Capacitance	Coss	V _{GS} = 0 V		410		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		150		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 15 V, I _D = 32 A		9.6		ns
Rise Time	tr	V _{GS} = 10 V		5.1		ns
Turn-off Delay Time	t _{d(off)}	R _G = 10 Ω		38		ns
Fall Time	tr			10		ns
Total Gate Charge	QG	V _{DD} = 24 V		23		nC
Gate to Source Charge	Q _{GS}	V _{GS} = 10 V		4.3		nC
Gate to Drain Charge	Qgd	I _D = 64 A		6		nC
Body Diode Forward Voltage Note	VF(S-D)	IF = 64 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 64 A, VGS = 0 V		31		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/ <i>µ</i> s		25		nC

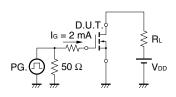
Note Pulsed: PW \leq 350 μ s, Duty Cycle \leq 2%

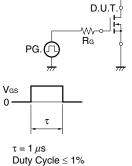
TEST CIRCUIT 1 AVALANCHE CAPABILITY

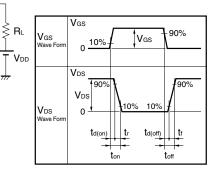
TEST CIRCUIT 2 SWITCHING TIME



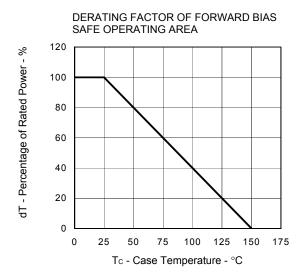
TEST CIRCUIT 3 GATE CHARGE



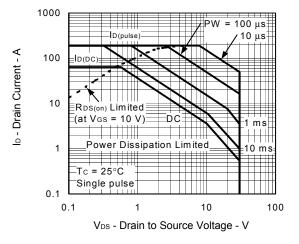


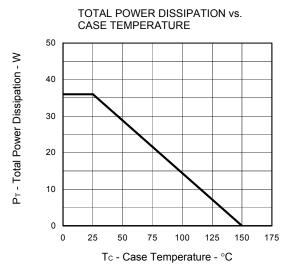


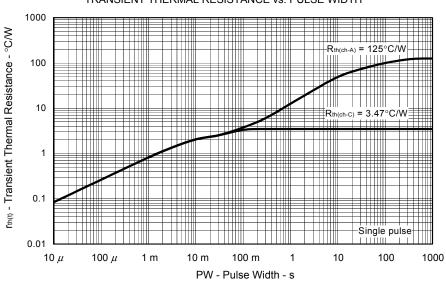
TYPICAL CHARACTERISTICS (T_A = 25°C)



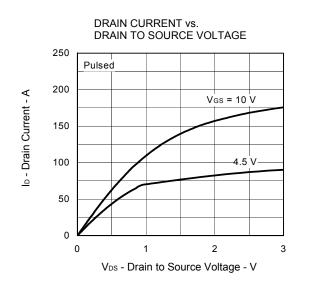






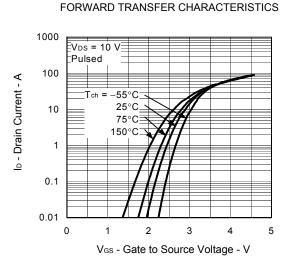




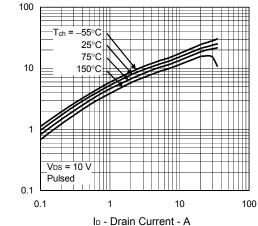


GATE CUT-OFF VOLTAGE vs.

CHANNEL TEMPERATURE

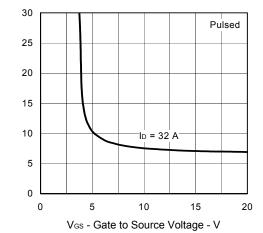


FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT





DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



DRAIN CURRENT 30 Pulsed

3

2.5

2

1.5

1

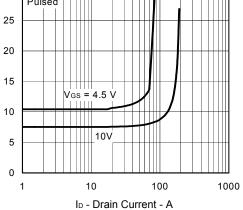
0.5

0

-50

0

V_{GS(off)} - Gate Cut-off Voltage - V



50

Tch - Channel Temperature - °C

DRAIN TO SOURCE ON-STATE RESISTANCE vs.

150

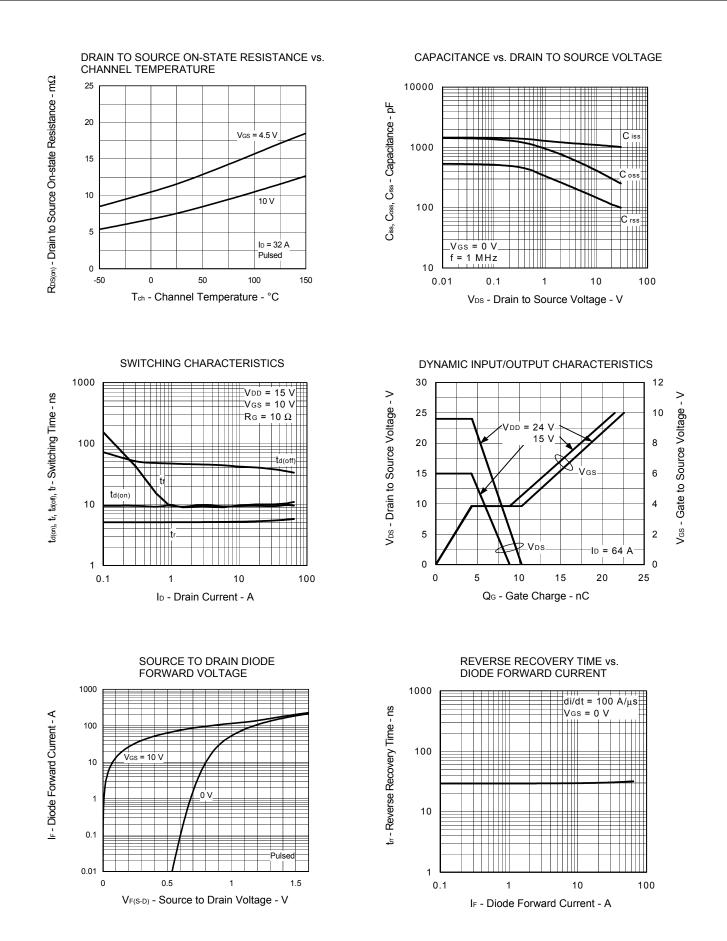
100

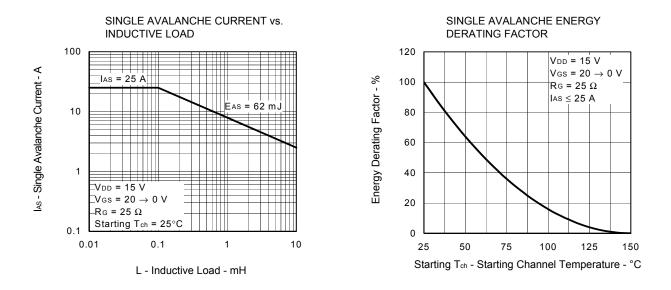
V_{DS} = 10 V

ID = 1 mA

 $R_{DS(on)}$ - Drain to Source On-state Resistance - $m\Omega$

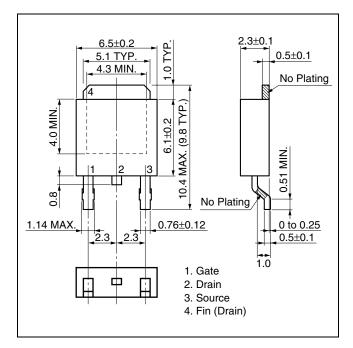
 $R_{DS(on)}$ - Drain to Source On-state Resistance - m Ω



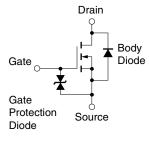


★ PACKAGE DRAWING (Unit: mm)

TO-252 (MP-3ZK)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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